

TITLE	SPECIFICATIONS FOR Inf	rared Array Sensor	PAGE 2/26
NAME	Infrared Array Sensor	"Grid-EYE"	AMG88**
4-2	Main Functions		
	Item	Value	
	Pixel number	64 (8×8 Matrix)	
	External Interface	I ² C (fast mode)	
	Frame rate	Typ.10 frames/sec or Typ.1 f	frame/sec
	Operating Mode	Normal	
		Sleep	
		Stand-by (10sec or 60sec int	termittence)

0.25℃

 $-20^{\circ}\mathrm{C}\sim80^{\circ}\mathrm{C}$

0.0625°C

Temperature Output

2 (I²C Slave Address)

No moving average or Twice moving average

4-3 Absolute Maximum Ratings

Output Mode

Calculate Mode

Temperature Output Resolution

Thermistor Output Temperature Range

Thermistor Output Resolution

Number of Sensor Addresses

Item	Specification	Terminal
Applied voltage	-0.3~6.5V	VDD, VPP
Input/Output voltage	-0.3~Vdd+0.3V	SCL, SDA, AD_SELECT
Output current	-10~10mA	INT, SDA
ESD (Human Body Model)	1kV	All Terminals
ESD (Machine Model)	200V	All Terminals

4-4 Ratings

Item	Specification	
	High gain	Low gain
Applied voltage	$3.3V \pm 0.3V$ or 5.0	$V\pm0.5V$
Temperature Range of Measuring Object	0°C∼80°C	-20°C∼100°C
Operating temperature	0°C∼80°C	-20°C∼80°C
Storage temperature	-20°C∼80°C	

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4-5 Characteristics

Item	Specification	
	High gain	Low gain
Temperature Accuracy	Within Typ. $\pm 2.5^\circ\!\mathrm{C}$	Within Typ. $\pm 3.0^\circ\!\!\mathrm{C}$
Rated detection distance *1	5m (Max.)	
Field of View	Typ. 60° (Horizontal, Vert	cical)
Optical Axis Gap	Within Typ. $\pm 5.6^{\circ}$ (Horizo	ontal, Vertical)
Current Consumption	Typ. 4.5mA (normal mode)	
	Typ. 0.2mA (sleep mode)	
	Typ. 0.8mA (stand-by mode)	
Setup Time	Typ. 50msec (Time to enable	Communication after Setup)
	Typ. 15sec (Time to stabil	ize Output after Setup)

*1 • To have more than 4°C of temperature difference from background
 • Detection object size: 700×250mm (Assumable human body size)

4-6 Electric characteristics

(1) Characteristics of the SDA and SCL $\rm I/O$ stages

parameter	symbol	Min.	Max.	unit
Low level input voltage	V _{IL}	-0.3	0.3 \times VDD	V
High level input voltage	V_{IH}	0.7 \times VDD	VDD+0.3	V
Hysteresis (SDA, SCL)	$V_{\rm hys}$	$0.05 \times VDD$		V
Low level output voltage	V _{OL}	0	0.4	V
(at 3mA sink current)				
Output fall time from $V_{\rm IHmin}$ to $V_{\rm ILmax}$ with	t_{of}	20+C _b	250	ns
a bus capacitance from 10pF to 400pF				
Pulse width of spikes which must be	t_{SP}	0	50	ns
suppressed by the input filter				
Input current each I/O pin with an input	II	-10	10	μ A
voltage between 0.1×VDD \sim 0.9×VDD				
Capacitance for each I/O pin	C _i	-	10	pF

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NAME

Infrared Array Sensor "Grid-EYE"

AMG88**

(2) Characteristics of the SDA and SCL bus lines

parameter	symbol	Min.	Max.	unit
SCL clock frequency	f_{SCL}	0	400	kHz
Hold time (repeated) START condition.	t _{HD;STA}	600	-	ns
Low period of the SCL clock	t _{LOW}	1.3		μs
High period of the SCL clock	T _{high}	0.6		μs
Set-up time for a repeated START condition	t _{su;sta}	0.6		μs
Data hold time	t _{HD;DAT}	0	900	ns
Data set-up time	t _{su;dat}	100		ns
Rise time of both SDA and SCL signals (f _{SCL} >100kHz)	t _r	20+0. 1 ×С _ь	300	ns
Rise time of both SDA and SCL signals (f _{SCL} ≦100kHz)	t _r		1000	ns
Fall time of both SDA and SCL signals	t _f	20+0.1 ×C _b	300	ns
Set-up time for STOP condition	t _{su;sto}	600		ns
Bus free time between a STOP and START condition	t _{BUF}	1300		ns
Capacitive load for each bus line	C _b		400	pF

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IAME		Infr	ared Array Sensor "Grid-EYE"		AMG88**
4-8	Pleas		tion o product drawing about pin assignment. connect wires in (NC) terminals.		
	Terminal No.	Name	Function	I/0	Remarks
	1	(NC)	_		
	2	SDA	I ² C data line	I/0	
	3	SCL	I²C clock line	Ι	
	4	INT	<pre>Interrupt flag -This flag indicates whether Interrupt is generated or not when INT control register is activated.</pre>	0	Please refer t section 4-10(4
	5	AD_SELECT	Sensor address setting -2 number settable with connecting to VDD or GND.	Ι	Please refer t section 4-9
	6	GND	OV	Ι	
	\bigcirc	(NC)	_		
	8	(NC)	-		
	9	VDD	DC3.3V or DC5V	Ι	
	10	AVDD-PC	Capacitor connected	Ι	Please refer t section 4-9
	11)	(NC)	-		
	12	DVDD-PC	Capacitor connected	Ι	Please refer t section 4-9
	13	VPP	VDD connection	Ι	
	(14)	(NC)	_		



TITLE	SPI	ECIFICA	TIONS I	FOR Inf:	rared A	Array Se	ensor		PAC	GE S	0/26
NAME	In	frared	Array S	Sensor'	"Grid-E	YE"				AMO	388 * *
Re Tai ca it (1) Pow Re Wi	cription gisters s ke care t use of ma s perform ver Contro gister fo th settin *Writing	hown be o avoid king pr ance. ol Regis r setti g provi	elow ar d writi roper o ster .ng ope .ded co	ng regi peratio rating mmand,	ster an n impos mode of changin	nd bit w ssible a f device ng to ea	which a and cau e. ach ope	re not sing a rating	deterio mode i:	oration s possil	in ole.
	*Reading										id 0x00)
address	register	R/W	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initial value
0x00	PCTL	R/W				PCTL	[7:0]				0x00
0x10 0x20 0x21	Stand-by	y mode (y mode (10sec ir	atermitte atermitte cam of Op	perating	g mode]		0x20 0x21			
		Slee	-			<u>0x0</u>		, n	und-by node	DATE :	Aug. 30. 201
	Pa	nasonic	e Corpo	ration		REFER				DATE :	Aug. 30.

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R		frared	Array S	Sensor	"Grid-E	YE"				AMG	3 88**
T	eset Regist egister on riting in here are t Flag Rese and Inter Initial F	ly for specifi wo kind et can crupt T	ic code ls of S all cle able (C	and re oftware ear the 0x10~0x	gister Reset. Status (17).	makes S Regist	er (0x0)4) ,In ⁻	terrupt	Flag,	
address	register	R/W	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initial value
0x01	RST	W				RST	[7:0]				0x00
			command			-	ating mo				
	-		0x30 0x3F				ag reset tial rese				
	-		else			1111 0	_				
	L										
address	1: 1FPS 0: 10FPS register	R/W	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initial
	U										
0x02	FPSC	R/W	-	-	-	-	-	_	-	FPS	value 0x00
0x02	terrupt Co Register f bit1: INTM 1: Abso 0: Diff bit0: INTE 1: INT	ontrol 1 for sett OD lute Va ference N Output	ting In alue In Interr active	terrupt terrupt upt Mod	Mode e	- .on.	_	-	-	FPS	value
0x02 (4) In	terrupt Co Register f bit1: INTM 1: Abso 0: Diff bit0: INTE	ontrol 1 for sett OD lute Va ference N Output	ting In alue In Interr active	terrupt terrupt upt Mod	Mode e	- .on.	- bit3	- bit2	- bit1	FPS	value 0x00 Initial
0x02	terrupt Co Register f bit1: INTM 1: Abso 0: Diff bit0: INTE 1: INT 0: INT	ontrol 1 for sett OD lute Va ference N Output Output	ting In alue In Interr active reacti	terrupt terrupt upt Mod ve (Hi-	Mode e Z)		- bit3	-	- bit1 INTMOD		value 0x00

AME					iuicu i	liay 5	ensor		PAG	iΕ]	11/26
	In	frared	Array	Sensor	"Grid-E	EYE"				AMO	G88 * *
	atus Regis egister fo		readin	g to in	ndicate	Overf]	ow Flag	g and Ir	nterrup [.]	t Flag.	
bi		rmisto	-	rature istor (-		ow 0xFFF)				
bi	t2: OVF_IR 1: Tem	S peratu	re Outp	ut Over	flow		30∼0xFF		FF)		
bi		-	Outbre f Inter		ble Reg	gister	(0x10~	0x17) :	Except	t for O	x00)
address	register	R/W	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initial value
0x04	STAT	R	-	-	-	-	OVF_THS	OVF_IRS	INTF	-	0x00
bi	t3: OVT_CL	.R			rns 0x00 Output		ow Flag	g Clear	-	t Flag.	
bi	t3: OVT_CL 1: The t2: OVS_CL 1: Tem t1: INTCLR	R rmistor R peratur	r Tempe	rature ut Over	Output	0verf]		g Clear		J	
bi	t3: OVT_CL 1: The t2: OVS_CL 1: Tem t1: INTCLR	R rmistor R peratur	r Tempe re Outp	rature ut Over	Output	0verf]		clear bit2	bit1	bit0	Initial
bi bi	t3: OVT_CL 1: The t2: OVS_CL 1: Tem t1: INTCLR 1: Int	R rmistor R peratur errupt	r Tempe re Outp Flag C	rature ut Over lear	Output	Overf] lag Cle	bit3		bit1		Initial value 0x00
bi bi address	t3: OVT_CL 1: The t2: OVS_CL 1: Tem t1: INTCLR 1: Int register	R rmistor R peratur errupt R/W	r Tempe re Outp Flag C bit7	rature ut Over lear bit6	Output flow Fibit5	Overf] lag Cle bit4 -	ear bit3 OVT_CLR	bit2 OVS_CLR	bit1 INTCLR	bit0	value
bi bi address	t3: OVT_CL 1: The t2: OVS_CL 1: Tem t1: INTCLR 1: Int register	R rmistor R peratur errupt R/W	r Tempe re Outp Flag C bit7	rature ut Over lear bit6	Output flow Fibit5	Overf] lag Cle bit4 -	bit3	bit2 OVS_CLR	bit1 INTCLR	bit0 _	value

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IAME	In	nfrared	Array S	Sensor	"Grid-E	YE"				1	AMG88	**
	Average Reg Register fo bit5: MAMO 1: Twic	or setti	-	-	-	-	ode.					
address	register	R/W	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit	0	nitial value
0x07	AVE	R/W	-	-	MAMOD	-	-	-	-	-		0x00
	The method In case of	setting	; on)	ving av	verage (-	node is In case	of set	ting of	ff)		
	address	R/W		alue			addres	is I	R/W	valu		
	0x1F	W)x50			0x1F		W	0x5		
	0x1F 0x1F	W		0x45 0x57			0x1F 0x1F		W	0x4 0x5		
	0x07	W)x20			0x07		W	0x0		
	0x1F	W	(0x00			0x1F		W	0x0	00	
(8)]	Interrupt La Register f 1 LSB has and it is	for sett 12 bit	ting up resolu	tion (1	ll bit +	+ sign)	which		-			<u>}</u>
(8)] address	Register f 1 LSB has	for sett 12 bit	ting up resolu	tion (1	ll bit +	+ sign)	which n.	is equi	ivalent	to O		Initia
	Register f 1 LSB has and it is	for sett 12 bit indicat	ting up resolu ted as	tion (1 two's c	l1 bit + compleme	+ sign) ent form bit4	which n.	is equi	ivalent	to O). 25℃	Initia
address	Register f 1 LSB has and it is register	for sett 12 bit indicat	ting up resolu ted as	tion (1 two's c	l1 bit + compleme	+ sign) ent form bit4	which n. bit3	is equi	ivalent	to 0). 25℃	Initia
address 0x08	Register f 1 LSB has and it is register INTHL	for sett 12 bit indicat R/W	ting up resolu ted as	tion (1 two's c	l1 bit + compleme	+ sign) ent form bit4 INT_LV	which n. bit3	is equi bit:)] INT_L	ivalent 2 bi [.]	to 0). 25℃	Initia value
address 0x08 0x09 0x0A 0x0B	Register f 1 LSB has and it is register INTHL INTHH INTLL INTLH	for sett 12 bit indicat	ting up resolu ted as	tion (1 two's c	l1 bit + compleme	+ sign) ent form bit4 INT_LV INT_LV	which n. /L_H [7:0 /L_L [7:0	is equi bit:)] INT_L)] INT_L	ivalent 2 bi [.]	to 0 t1 1:8]). 25℃	Initia
address 0x08 0x09 0x0A	Register f 1 LSB has and it is register INTHL INTHH INTLL	for sett 12 bit indicat R/W	ting up resolu ted as	tion (1 two's c	l1 bit + compleme	+ sign) ent form bit4 INT_LV INT_LV	which n. bit3 /L_H [7:0	is equi bit:)] INT_L)] INT_L	ivalent 2 bi ⁻ VL_H [1:	to 0 t1 1:8]). 25℃	Initia value
address 0x08 0x09 0x0A 0x0B 0x0C 0x0D	Register f 1 LSB has and it is register INTHL INTHL INTLH INTLH IHYSL IHYSH IHYSH INT_LVL_H [J Interrupt I Interrupt I Interrupt I Interrupt C INT_LVL_L [J] Interrupt I Interrupt C INT_HYS [11:	for sett 12 bit indicat R/W R/W 11:0]: Level up Dutput a 11:0]: Level lo Dutput a :0]:	pper linand Int	mit set errupt	ll bit + compleme bit5 - - - - - - - - - - - - - - - - - - -	+ sign) ent form bit4 INT_LV INT_LV INT_LV INT_L INT_F nen the Fable a:	which n. /L_H [7:0 /L_L [7:0] /YS [7:0] /YS [7:0] //L_L [7:0]	is equi bit: D] INT_L INT_L INT_ is uppe	VL_H [1: VL_L [1: HYS [11 er than	to 0 t1 1:8] :8] the the).25℃ bit0	Initia value 0x00
address 0x08 0x09 0x0A 0x0B 0x0C 1 0x0D 1	Register f 1 LSB has and it is register INTHL INTHH INTLL INTLH INTLH IHYSL IHYSL IHYSH CNT_LVL_H [1 Interrupt I Interrupt I Interrupt I Interrupt I	for sett 12 bit indicat R/W R/W 11:0]: Level up Dutput a 11:0]: Level lo Dutput a :0]: Interru esis Lev	bit7 bit7 oper li and Int ower li and Int upt Hys yel app	mit set errupt teresis lied to	ll bit + compleme bit5 - - - - - - - - - - - - - - - - - - -	+ sign) ent form bit4 INT_LV INT_LV INT_LV INT_F nen the fable a: nen the fable a: nen the fable a:	which n. bit3 /L_H [7:0] /L_L [7:0] WS [7:0] WS [7:0] WS [7:0] value re set. value re set.	is equi bit: D] INT_L D] INT_L INT_ INT_ INT_ INT_ INT_ INT_ INT_ INT_	VL_H [1: VL_L [1: VL_L [1: HYS [11 er than er than enerate ower va	to 0 t1 1:8] 1:8] :8] the the d, 1ue.).25℃ bit0	Initia value 0x00

TITLE		SPECIFI	CATIONS	FOR In	ıfrared	Array S	ensor		PAGI	E 13	3/26
NAME		Infrare		AMG8	38**						
9)) Thermisto Thermist Thermist Temperat 1 LSB ha	or Temp or Temp ure Dat s 12 bi	erature erature a is 12 t resolu	Data. bit da ution wi	ta and hich is	2 byte d equival	lata.			icate	
	it is in Main tem										
address	register	R/W	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initial value

address	register	R/W	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initial value
0x0E	TTHL	R	Τ7	T6	Τ5	T4	Т3	T2	T1	TO	0x00
0x0F	TTHH	R	-	-	-	_	+/-	T10	Т9	Τ8	0x00

temperature	Binary number	HEX number
+125°C	0111_1101_0000	0x7D0
+25°C	0001_1001_0000	0x190
+0. 25°C	0000_0000_0100	0x004
0°C	0000_0000_0000	0x000
−0. 25°C	1000_0000_0100	0x804
−20°C	1001_0100_0000	0x940

(10) Interrupt Table Register

Register for reading only to indicate pixels which temperature outputs are over the threshold.

address	register	R/W	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initial value
0x10	INT0	R	PIX08	PIX07	PIX06	PIX05	PIX04	PIX03	PIX02	PIX01	0x00
0x11	INT1	R	PIX16	PIX15	PIX14	PIX13	PIX12	PIX11	PIX10	PIX09	0x00
0x12	INT2	R	PIX24	PIX23	PIX22	PIX21	PIX20	PIX19	PIX18	PIX17	0x00
0x13	INT3	R	PIX32	PIX31	PIX30	PIX29	PIX28	PIX27	PIX26	PIX25	0x00
0x14	INT4	R	PIX40	PIX39	PIX38	PIX37	PIX36	PIX35	PIX34	PIX33	0x00
0x15	INT5	R	PIX48	PIX47	PIX46	PIX45	PIX44	PIX43	PIX42	PIX41	0x00
0x16	INT6	R	PIX56	PIX55	PIX54	PIX53	PIX52	PIX51	PIX50	PIX49	0x00
0x17	INT7	R	PIX64	PIX63	PIX62	PIX61	PIX60	PIX59	PIX58	PIX57	0x00

PIXn:

Setting pixels over the threshold.

1: Pixel* interrupt is generated.

0: Pixel* interrupt is not generated.

Interrupt Table is renewed in timing with when output data is renewed. Interrupt Table is possible to be cleared by reset resister.

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(11) Temperature Register

Register for reading only to indicate temperature data per 1 pixel. Temperature Data of each pixel is 12 bit data and 2 byte data. 1 LSB has 12 bit resolution (11 bit + sign) which is equivalent to 0.25°C and it is indicated as two's complement form. Main temperature data are shown below.

address	register	R/W	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initial value
0x80	T01L	R	Τ7	Τ6	Τ5	T4	Т3	T2	T1	TO	0x00
0x81	T01H	R	-	-	-	-	+/-	T10	Т9	T8	0x00

temperature	Binary number	HEX number
+125°C	0001_1111_0100	0x1F4
+25°C	0000_0110_0100	0x064
+0. 25°C	0000_0000_0001	0x001
0°C	0000_0000_0000	0x000
−0. 25°C	1111_1111_1111	0xFFF
−25°C	1111_1001_1100	0xF9C
−55°C	1111_0010_0100	0xF24

Supplement)

Temperature Data of Pixel $1 \sim 64$ (0x80 \sim 0xFF) are renewed in a lump in timing with no instruction from external Master.

(Renewal time depends on the setting frame rate.)

Because of reading $0x80{\sim}0xFF$ at once,

old and new temperature data never be mingled in 64 pixels data.

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NAME	Infrare	d Array Sens	or "Grid-EYE"		AMG88**
-11 Reg	ister Map				
	ite ∛ Read/Write	column R/W	: both of Read & Write, R : Read on	nly, W:	Write only
Address	Register Name	Read/Write	Description		Initial value
0x00	PCTL	R/W	Set operating mode (Normal, Slee	p etc.)	0x00
0x01	RST	W	Software Reset		0x00
0x02	FPSC	R/W	Frame rate		0x00
0x03	INTC	R/W	Interrupt Function		0x00
0x04	STAT	R	Interrupt Flag, low voltage Flag		0x00
0x05	SCLR	W	Interrupt Flag Clear		0x00
0x06			Reserved		
0x07	AVE	R	Moving Average Output Mode		0x00
0x08	INTHL	R/W	Interrupt upper value (Upper lev	vel)	0x00
0x09	INTHH	R/W	Interrupt upper value (Upper lev	vel)	0x00
0x0A	INTLL	R/W	Interrupt lower value (Lower lev	vel)	0x00
0x0B	INTLH	R/W	Interrupt lower value (upper lev	vel)	0x00
0x0C	IHYSL	R/W	Interrupt hysteresis value (Lower	rlevel)	0x00
0x0D	IHYSH	R/W	Interrupt hysteresis value (Upper	level)	0x00
0x0E	TTHL	R	Thermistor Output Value (Lower	level)	0x00
0x0F	TTHH	R	Thermistor Output Value (Upper		0x00
0x10	INTO	R	Pixel 1~8 Interrupt Result		0x00
0x11	INT1	R	Pixel 9~16 Interrupt Result		0x00
0x12	INT2	R	Pixel 17~24 Interrupt Result		0x00
0x13	INT3	R	Pixel 25~32 Interrupt Result		0x00
0x14	INT4	R	Pixel 33~40 Interrupt Result		0x00
0x15	INT5	R	Pixel 41~48 Interrupt Result		0x00
0x16	INT6	R	Pixel 49~56 Interrupt Result		0x00
0x17	INT7	R	Pixel 57~64 Interrupt Result		0x00
0x18			Reserved		
0x19			Reserved		
0x1A			Reserved		
0x1B			Reserved		
0x1C			Reserved		
0x1D			Reserved		
0x1E			Reserved		
0x1E			Reserved		
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AME	Infrare	ed Array Sens	or "Grid-EYE"	AMG88**
Address	Register Name	Read/Write	Description	Initial val
0x80	T01L	R	Pixel 1 Output Value (Lower Leve	1) 0x00
0x81	TO1H	R	Pixel 1 Output Value (Upper Leve	1) 0x00
0x82	T02L	R	Pixel 2 Output Value (Lower Leve	1) 0x00
0x83	Т02Н	R	Pixel 2 Output Value (Upper Leve	1) 0x00
0x84	T03L	R	Pixel 3 Output Value (Lower Leve	1) 0x00
0x85	ТОЗН	R	Pixel 3 Output Value (Upper Leve	1) 0x00
0x86	T04L	R	Pixel 4 Output Value (Lower Leve	1) 0x00
0x87	Т04Н	R	Pixel 4 Output Value (Upper Leve	1) 0x00
0x88	T05L	R	Pixel 5 Output Value (Lower Leve	1) 0x00
0x89	Т05Н	R	Pixel 5 Output Value (Upper Leve	1) 0x00
0x8A	T06L	R	Pixel 6 Output Value (Lower Leve	1) 0x00
0x8B	Т06Н	R	Pixel 6 Output Value (Upper Leve	1) 0x00
0x8C	T07L	R	Pixel 7 Output Value (Lower Leve	1) 0x00
0x8D	Т07Н	R	Pixel 7 Output Value (Upper Leve	1) 0x00
0x8E	T08L	R	Pixel 8 Output Value (Lower Leve	1) 0x00
0x8F	Т08Н	R	Pixel 8 Output Value (Upper Leve	1) 0x00
0x90	T09L	R	Pixel 9 Output Value (Lower Leve	1) 0x00
0x91	ТОЭН	R	Pixel 9 Output Value (Upper Leve	1) 0x00
0x92	T10L	R	Pixel 10 Output Value (Lower Lev	el) 0x00
0x93	Т10Н	R	Pixel 10 Output Value (Upper Lev	el) 0x00
0x94	T11L	R	Pixel 11 Output Value (Lower Lev	el) 0x00
0x95	T11H	R	Pixel 11 Output Value (Upper Lev	el) 0x00
0x96	T12L	R	Pixel 12 Output Value (Lower Lev	e1) 0x00
0x97	Т12Н	R	Pixel 12 Output Value (Upper Lev	el) 0x00
0x98	T13L	R	Pixel 13 Output Value (Lower Lev	el) 0x00
0x99	Т13Н	R	Pixel 13 Output Value (Upper Lev	el) 0x00
0x9A	T14L	R	Pixel 14 Output Value (Lower Lev	el) 0x00
0x9B	T14H	R	Pixel 14 Output Value (Upper Lev	el) 0x00
0x9C	T15L	R	Pixel 15 Output Value (Lower Lev	el) 0x00
0x9D	Т15Н	R	Pixel 15 Output Value (Upper Lev	el) 0x00
0x9E	T16L	R	Pixel 16 Output Value (Lower Lev	el) 0x00
0x9F	Т16Н	R	Pixel 16 Output Value (Upper Lev	el) 0x00

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AME	Infran	red Array Ser	nsor "Grid-EYE"		AMG88**
Address	Register Name	Read/Write	Description		Initial val
0xA0	T17L	R	Pixel 17 Output Value (Lower Leve	1)	0x00
0xA1	Т17Н	R	Pixel 17 Output Value (Upper Leve	1)	0x00
0xA2	T18L	R	Pixel 18 Output Value (Lower Leve	1)	0x00
0xA3	Т18Н	R	Pixel 18 Output Value (Upper Leve	1)	0x00
0xA4	T19L	R	Pixel 19 Output Value (Lower Leve	1)	0x00
0xA5	Т19Н	R	Pixel 19 Output Value (Upper Leve	1)	0x00
0xA6	T20L	R	Pixel 20 Output Value (Lower Leve	1)	0x00
0xA7	Т20Н	R	Pixel 20 Output Value (Upper Leve	1)	0x00
0xA8	T21L	R	Pixel 21 Output Value (Lower Leve	1)	0x00
0xA9	Т21Н	R	Pixel 21 Output Value (Upper Leve	1)	0x00
OxAA	T22L	R	Pixel 22 Output Value (Lower Leve	1)	0x00
0xAB	Т22Н	R	Pixel 22 Output Value (Upper Leve	1)	0x00
0xAC	T23L	R	Pixel 23 Output Value (Lower Leve	1)	0x00
OxAD	Т23Н	R	Pixel 23 Output Value (Upper Leve	1)	0x00
OxAE	T24L	R	Pixel 24 Output Value (Lower Leve	1)	0x00
0xAF	Т24Н	R	Pixel 24 Output Value (Upper Leve	1)	0x00
0xB0	T25L	R	Pixel 25 Output Value (Lower Leve	1)	0x00
0xB1	Т25Н	R	Pixel 25 Output Value (Upper Leve	1)	0x00
0xB2	T26L	R	Pixel 26 Output Value (Lower Leve	1)	0x00
0xB3	Т26Н	R	Pixel 26 Output Value (Upper Leve	1)	0x00
0xB4	T27L	R	Pixel 27 Output Value (Lower Leve	1)	0x00
0xB5	Т27Н	R	Pixel 27 Output Value (Upper Leve	1)	0x00
0xB6	T28L	R	Pixel 28 Output Value (Lower Leve	1)	0x00
0xB7	Т28Н	R	Pixel 28 Output Value (Upper Leve	1)	0x00
0xB8	T29L	R	Pixel 29 Output Value (Lower Leve	1)	0x00
0xB9	Т29Н	R	Pixel 29 Output Value (Upper Leve	1)	0x00
0xBA	T30L	R	Pixel 30 Output Value (Lower Leve	1)	0x00
0xBB	ТЗОН	R	Pixel 30 Output Value (Upper Leve	1)	0x00
0xBC	T31L	R	Pixel 31 Output Value (Lower Leve	1)	0x00
0xBD	Т31Н	R	Pixel 31 Output Value (Upper Leve	1)	0x00
0xBE	T32L	R	Pixel 32 Output Value (Lower Leve	1)	0x00
0xBF	Т32Н	R	Pixel 32 Output Value (Upper Leve	1)	0x00

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ITLE	SPECIF	TCATIONS FOR	Infrared Array Sensor	PAGE 18/26
AME	Infran	red Array Ser	nsor "Grid-EYE"	AMG88**
			I	
Address	Register Name	Read/Write	Description	Initial valu
0xC0	T33L	R	Pixel 33 Output Value (Lower Level) 0x00
0xC1	ТЗЗН	R	Pixel 33 Output Value (Upper Level) 0x00
0xC2	T34L	R	Pixel 34 Output Value (Lower Level) 0x00
0xC3	Т34Н	R	Pixel 34 Output Value (Upper Level) 0x00
0xC4	T35L	R	Pixel 35 Output Value (Lower Level) 0x00
0xC5	Т35Н	R	Pixel 35 Output Value (Upper Level) 0x00
0xC6	T36L	R	Pixel 36 Output Value (Lower Level) 0x00
0xC7	Т36Н	R	Pixel 36 Output Value (Upper Level) 0x00
0xC8	T37L	R	Pixel 37 Output Value (Lower Level) 0x00
0xC9	Т37Н	R	Pixel 37 Output Value (Upper Level) 0x00
0xCA	T38L	R	Pixel 38 Output Value (Lower Level) 0x00
0xCB	Т38Н	R	Pixel 38 Output Value (Upper Level) 0x00
0xCC	T39L	R	Pixel 39 Output Value (Lower Level) 0x00
0xCD	Т39Н	R	Pixel 39 Output Value (Upper Level) 0x00
0xCE	T40L	R	Pixel 40 Output Value (Lower Level) 0x00
0xCF	Т40Н	R	Pixel 40 Output Value (Upper Level	0x00
0xD0	T41L	R	Pixel 41 Output Value (Lower Level) 0x00
0xD1	T41H	R	Pixel 41 Output Value (Upper Level	0x00
0xD2	T42L	R	Pixel 42 Output Value (Lower Level	0x00
0xD3	Т42Н	R	Pixel 42 Output Value (Upper Level	0x00
0xD4	T43L	R	Pixel 43 Output Value (Lower Level	0x00
0xD5	Т43Н	R	Pixel 43 Output Value (Upper Level	0x00
0xD6	T44L	R	Pixel 44 Output Value (Lower Level	0x00
0xD7	T44H	R	Pixel 44 Output Value (Upper Level	0x00
0xD8	T45L	R	Pixel 45 Output Value (Lower Level	0x00
0xD9	Т45Н	R	Pixel 45 Output Value (Upper Level	0x00
OxDA	T46L	R	Pixel 46 Output Value (Lower Level	0x00
0xDB	Т46Н	R	Pixel 46 Output Value (Upper Level	0x00
0xDC	T47L	R	Pixel 47 Output Value (Lower Level	0x00
OxDD	Т47Н	R	Pixel 47 Output Value (Upper Level	0x00
0xDE	T48L	R	Pixel 48 Output Value (Lower Level	0x00
0xDF	T48H	R	Pixel 48 Output Value (Upper Level) 0x00

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ITLE			l Infrared Array Sensor	PAGE 19/26
AME	E Infrared Array Sensor "Grid-EYE"			AMG88**
Address	Register Name	Read/Write	Description	Initial valu
0xE0	T49L	R	Pixel 49 Output Value (Lower Level) 0x00
0xE1	Т49Н	R	Pixel 49 Output Value (Upper Level) 0x00
0xE2	T50L	R	Pixel 50 Output Value (Lower Level) 0x00
0xE3	Т50Н	R	Pixel 50 Output Value (Upper Level) 0x00
0xE4	T51L	R	Pixel 51 Output Value (Lower Level	0x00
0xE5	Т51Н	R	Pixel 51 Output Value (Upper Level) 0x00
0xE6	T52L	R	Pixel 52 Output Value (Lower Level) 0x00
0xE7	Т52Н	R	Pixel 52 Output Value (Upper Level) 0x00
0xE8	T53L	R	Pixel 53 Output Value (Lower Level) 0x00
0xE9	Т53Н	R	Pixel 53 Output Value (Upper Level) 0x00
0xEA	T54L	R	Pixel 54 Output Value (Lower Level) 0x00
0xEB	Т54Н	R	Pixel 54 Output Value (Upper Level) 0x00
0xEC	T55L	R	Pixel 55 Output Value (Lower Level) 0x00
OxED	Т55Н	R	Pixel 55 Output Value (Upper Level) 0x00
0xEE	T56L	R	Pixel 56 Output Value (Lower Level) 0x00
0xEF	Т56Н	R	Pixel 56 Output Value (Upper Level) 0x00
0xF0	T57L	R	Pixel 57 Output Value (Lower Level) 0x00
0xF1	Т57Н	R	Pixel 57 Output Value (Upper Level) 0x00
0xF2	T58L	R	Pixel 58 Output Value (Lower Level) 0x00
0xF3	Т58Н	R	Pixel 58 Output Value (Upper Level) 0x00
0xF4	T59L	R	Pixel 59 Output Value (Lower Level) 0x00
0xF5	Т59Н	R	Pixel 59 Output Value (Upper Level) 0x00
0xF6	T60L	R	Pixel 60 Output Value (Lower Level) 0x00
0xF7	Т60Н	R	Pixel 60 Output Value (Upper Level) 0x00
0xF8	T61L	R	Pixel 61 Output Value (Lower Level) 0x00
0xF9	Т61Н	R	Pixel 61 Output Value (Upper Level) 0x00
0xFA	T62L	R	Pixel 62 Output Value (Lower Level	0x00
0xFB	Т62Н	R	Pixel 62 Output Value (Upper Level	0x00
0xFC	T63L	R	Pixel 63 Output Value (Lower Level	0x00
0xFD	Т63Н	R	Pixel 63 Output Value (Upper Level	0x00
0xFE	T64L	R	Pixel 64 Output Value (Lower Level	0x00
0xFF	Т64Н	R	Pixel 64 Output Value (Upper Level) 0x00

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TITLE	SPECIFICATIONS FOR Infrared Array Sensor	PAGE 20/26		
NAME	Infrared Array Sensor "Grid-EYE"	AMG88**		
5. L	ot No. of manufactured Data of manufactured : Expressed in $& \text{first} \rightarrow 01$ Month of manufactured : Expressed i $& \text{X}$ January $\rightarrow 01$ Year of manufactured : Expressed in of the year. $& \text{X}$ 2011 $\rightarrow 11$	n two digits.		
6.	 6. Safety Precautions Safety Precautions Safety Precautions Mead the following precautions to prevent injury or accidents. (Do not use these sensors under any circumstance in which the range of their ratings, environment conditions or other specifications are exceeded. Using the sensors in any way which causes their specifications to be exceeded may generate abnormally high levels of heat, emit smoke, etc., resulting in damage to the circuitry and possibly causing an accident. (Before connecting a connector, check the pin layout by referring to the connector formented properly. Take note that mistakes made in connection may cause unforeseen problems in operation, generate abnormally high levels of heat, emit smoke, etc., resulting in damage to the circuitry. (Do not use any Infrared Array Sensor which has been disassembled or remodeled. (Failure modes of sensors include short-circuiting, open-circuiting and temperature rises. If this sensor is to be used in equipment where safety is a prime consideration, examine the possible effects of these failures on the equipment concerned, and ensure safety by providing protection circuits or protection devices. Example Safety equipments and devices Burglar and disaster prevention devices Control and safety device for trains and motor vehicles. Temperature control device using sensor output data. Etc. 			
	Panasonic Corporation Automation Controls Business U	nit		

TITLE	SPECIFICATIONS FOR Infrare	d Array Sensor	PAGE 21/26			
NAME	Infrared Array Sensor "Gri	d-EYE"	AMG88**			
7. NOTE	7. NOTES					
7-1						
	The Infrared Array Sensor is a thermopile-typed infrared sensor which detects quantity of infrared ray. Generally, temperature accuracy will be degraded in the following situations. Be sure to verify performance and reliability under actual conditions of use and make any necessary temperature corrections.					
	• There is a heat emitting body located close to where the sensor is mounted.					
	• A flow of warm or cold air is hitti					
	• The temperature of the sensor is su	bject to sudden change.				
	• When an object made of glass, acrylic or other subject which far infrared rays have difficult passing through is located between the sensor and what is to be detected.					
	• A substance (dirt or water droplets) that makes it difficult for far infrared rays to pass through is attached to the sensor lens.					
7-2	Ambient operating conditions					
(1)	Temperature : Please refer to Rati	ngs.				
(2)	Humidity : 15% to 85% R.H. (No freez	ing nor condensation at lo	w temperature)			
(3)	(3) Atmospheric pressure : 86 to 106 kPa					
(4)	(4) Protect the sensor from impact and vibration, because there can cause damage that leads to malfunction and degraded performance.And avoid applying a load or impact since this will deform or scratch the lens, making proper operation impossible and causing a deterioration in its performance.					
(5)	(5) The sensors do not have a water-proof or dust-proof construction. Depending on the ambient operating conditions, some means of providing protection from water and dust and preventing the formation of ice and condensation must be provided prior to using the sensor. If condensation occurs, heat source detection response may become delayed by several seconds.					
(6)	(6) Please avoid using or storing the pressure sensor chip in a place exposed to corrosive gases (such as the gases given off by organic solvents, sulfurous acid gas, hydrogen sulfides, etc.) which will adversely affect the performance of the infrared array sensor.					
(7)	(7) Since the internal circuitry may be destroyed if an external surge voltages is supplied, provide an element which will absorb the surges.					
(8)	Malfunctioning may occur if the produ as that from static electricity, lig broadcasting station.					
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NAME	Infrared Array Sensor "Grid-EYE"	AMG88**

(9) Although the ambient temperature (humidity) range is a temperature (humidity) range which can operate a sensor continuously, the humidity range changes with temperature. So please use it in the humidity range shown below.And please avoid continuation use near a limit.

Generally under high temperature or high humidity, deterioration of electronic parts accelerates.

To ensure reliability, please verify quality under conditions of actual use. This humidity range does not guarantee durability ability.



7-3 Mounting

- Use lands on the printed-circuit boards to which the sensor can be securely fixed.Recommended printed-circuit board is FR4 (thickness 1.6mm).
- As for mounting unrecommended printed-circuit board, Please verify quality in advance.
- Malfunctioning may occur if much noise is present in the power supply used for this sensor. In order to prevent, in particular, superimposed noise, please install the recommended capacitor between the sensor input terminals (between VDD and GND) closest to the sensor (a position within 20 mm of the pattern circuit length). However, please reselect an ideal capacitor after performing tests on the actual equipment.
- Since the top surface (where the part number is visible) of the sensor is GND, please make sure that the metallic parts of other components do not come into contact.

7-4 Soldering

Due to the thermal capacity of the infrared array sensor is low, therefore, take steps to minimize the effects of external heat. Damage and changes to characteristics may occur due to heat deformation.

Use a non-corrosive resin type of flux.

(1) Manual soldering

- Set the soldering tip from 350 to $400^{\circ}C(30-60W)$, and solder within 3 seconds or less.
- Please note that output may be changed if the load is applied to the terminals when the soldering.
- Carefully clean the tip of soldering iron.

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	 (2) Reflow soldering The recommended reflow temperature profile conditions ar We recommend the screen solder printing method as the me Please refer to the recommended PC board specification d board foot pattern. Self alignment may not always work as expected, therefor the position of the terminals and pattern. The temperature of the profile is assumed to be a value printed wiring board of the terminal neighborhood. When you do the reflow solder to the back of the PC boar the sensor, please execute fixed processing, for instance, 	thod of cream. iagram for the PC e, please carefully measured with the d after the reflow of			
 (3) Solder reworking Finish reworking in one operation. For reworking of the solder bridge, use a soldering iron with a flat the Please do not add more flux when reworking. The temperature of the soldering tip must be under the above-mentioned temperature (4) When you cut or fold the PC board after mounting the sensor, be careful 					
	stress to the soldered parts.(5) The sensor terminals are designed to be exposed, so contact of the terminals with metal shards and the like will cause output errors. Therefore, please be careful not to touch the terminals with the metal piece or the hand.(6) To prevent the insulation of the PC board after soldering, please be careful not to place the chemicals on the sensor when coating.				
	Peak temperature				
	T3 T2 T1 T1 T1 T1 T1 T1 T1 T2 T3 t1	=150~180°C =230°C =Within 250°C =60~120 seconds =Within 30 seconds			
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TITLE	SPECIFICATIONS FOR Infrared Array Sensor	PAGE	24/26
NAME	Infrared Array Sensor "Grid-EYE"		AMG88**
7-5	 Connections Please perform connections correctly in accordance with diagram. In particular, be careful not to reverse wire will cause damage or degrade to the sensor. Please do not connect wires in an empty terminal. It cate When using the sensors with cables, it is recommended that and as short as possible be used in order to safeguard again 	the power s muses the se cables which	upply as this ensor breakdown. h are shielded
7-6	Cleaning Avoid ultrasonic cleaning since this may cause breaks o wiring.	or disconnec	ctions in the
7-7	Transportation and storage		
(1	 Extreme vibration and shock during transport will damage t Handle the outer box and reel with care. 	he sensor.	
(2	 2) Storage under extreme conditions will cause soldering degradated defects, and deterioration of the characteristics. The following storage conditions are recommended. Temperature : 0 to 45℃ Humidity : less than 70% R.H. Atmosphere : No harmful gasses such as sulfurous acid generations. 		
3)	 B) The sensors are sensitive to moisture and come in moisture Observe the following cautions when storing. After the moisture-proof package is unsealed, take the as soon as possible (within 1 week ≤ 30°C 60% R.H.) If the sensors are to be left in storage for a consider moisture-proof package has been unsealed, it is recomme another moisture-proof bag containing silica gel (within 1) 	sensors out able period ended to kee	t of storage l after the up them in
	* When mounting with solder, if thermal stress is applied to absorbed moisture, the moisture will vaporize, swelling will of the package will become stressed. This may cause the pa or crack. Therefore, please take caution and observe the s	ll occur, an ockage surfa	nd the inside ace to blister

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7-8	Other handling cautions		
	To assure reliability, check the sen Avoid any situation that may adverse		
	• This product may malfunction if drop Do not use if this happens.	ped on its own before i	t is installed.
	• Caution is required because writing 4-10 can be cause of malfunction and		
	• Caution is required because difference of connection can lead to breakdown.	es in the temperature ran	nge and the method
	 If the sensor get high frequency vib When the product get impulse like be ①touch to a object made of metal ②touch of mutual sensors 		of breakdown.
	• Since static charge can damage the s precautions.	ensor, bear in mind the	following handling
	①Plastic containers should not be u since they readily become charged.	-	ort the sensors
	②Please store or transport the prod occurrence of static electricity (f and protect the product using electricity)	for example, places with	h 45% to 60% humidity)
	③Implement static electricity preve has been opened.	ention measures once the	e product packaging
	• Any personnel handling the sense body grounded.	r should wear electrost	tatic clothing and be
	 Place an electrically conducting b used such as measuring instrument 		and ground any devices
	\cdot Use a soldering iron with a low		
	 Make sure that customer equipmen ④Since the internal circuitry may be supplied, provide an element which 	e destroyed if an exter	rnal surge voltage is
	Supplied, plotide di clement mile.	will appoint the barget	
	_		_
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8. Special remarks

Although the best attention will be paid for the quality controls of the products, please consider the followings :

- (1) To prevent unexpected failures as much as possible under the conditions not shown in this specifications, please let us know the detailed information on the application, such as the environmental, operational and mounting condition.
- (2) By any chance, if the failure of the product is considered to cause a personal injury or death or property damage, the safety rate should be added to the specified values shown in this specifications and the dual safety structure or circuit is recommended to be taken from the stand point of the Product Liability Indemnity.
- (3) We will either repair or replace any products or parts there of which prove to be defective against only the items written in this specifications within 1 year from the date of products acceptance at the site of delivery.
- (4) Following cases are not covered by this guarantee.
 - ① The case of other damage caused by the failure or defect of the product.
- ② The case that the product condition changed by handling, storage and/or transportation after delivery.
- ③ The case caused by the phenomenon which has never been discovered and is impossible to be foreknown with the existing technologies.
- ④ The case of force majeure, such as acts of God, public enemy or war, fires, floods and any other causes beyond the control of the people concerned.

9. Export control

[To Customers in Japan]

This product is restricted under Japan's "Foreign Exchange and Foreign Trade Law." An export permit from the Japanese government is required when you export or take this product outside Japan. (As of Apr.2011)

This product may not be used for any purpose other than those specified.

Reselling the product to third parties is prohibited.

When disposing of the product, it must first be converted into non-reusable and non-controlled form.

[To Customers Outside Japan]

This product is restricted under Japan's laws and regulations relating to security export control (Foreign Exchange and Foreign Trade Law).

We have obtained an export permit from the Japanese government to sell or provide this product to your company, subject to the following:

This product may not be used for any purpose other than those specified.

This product may be subject to further export restrictions under the laws and regulations of other countries (including your own).

Reselling the product to third parties is prohibited.

When disposing of the product, it must first be converted into non-reusable and non-controlled form.

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(3rd Angle System)

(JIS A-4)

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